

Appl. No. 10/676,961
Amdt. Dated 07/08/2005
Reply to final Office action of 05/31/2005

Amendments to the Abstract:

Please replace the Abstract with the Abstract that appears on the following page:

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ABSTRACT

An embodiment of the present invention is a technique to stack dies in a die assembly. A plurality of dies are stacked on top of one another in a staggered configuration such that an upper die top surface in a pair of adjacent dies faces downward or upward and is displaced by a first distance with respect to a lower die in the pair. The adjacent dies are attached by an adhesive layer between the adjacent dies.